



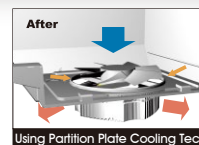
BK623



BK623

mATX Chassis

Features



* BK Series uses Intel Mt. Jade as Ref. Design

● 3rd Generation of Partition Plate Cooling Technology (PPCT)

PPCT is the world's first advanced thermal and acoustic cooling technology, which provides S.F.F. chassis with excellent thermal solutions while creating a quieter computing experience. PPCT does not require second fan; yet still provides an excellent thermal solution. The 3rd generation of PPCT includes an adjustable air duct for various CPU fans and efficiently eliminates overheat while enhances airflow of entire system. The new PPCT also supports the LGA1156 socket.

● Design Philosophy

To design a small 12.5L S.F.F. chassis with better thermal & acoustic performance than other bigger size chassis.

● Easy Integration

Compatible with all standard desktop components.
Easy system integration.

● Flexible Compatibility

Small but flexible enough to accommodate four full height PCI cards.

● Tool Free

Optional tool-free designs - ODD/FDD/HDD bays and side panel.

CASE SIZE	S.F.F. Tiny Tower Chassis
PROCESSOR	Support Dual Core and Quad Core Processor
EXTERNAL DRIVE BAY	5.25" x 1, 3.5" x 1
INTERNAL DRIVE BAY	3.5" x 1
FRONT PORTS	USB 2.0 x 4, HD Audio
DIMENSIONS (HxWxD)	12.7" x 5.5" x 10.8"
w/o Front Panel	323 x 140 x 276 mm (12.5L)
M/B	Micro-ATX
I/O EXPANSION SLOTS	Full Height Slot x 4
POWER SUPPLY	SFX 12V Form Factor, 300W
THERMAL SOLUTION	Intel Mt. Jade Ref. Design New Partition Plate Cooling Technology (New PPCT) No 2 nd Fan (Rear Fan) Needed
SAFETY	Meets RoHS, CE and FCC Class B Requirements
SECURITY	Padlock Loop / Kensington Slot
OPTIONAL	IEEE 1394 / IR / Removable Air Filter Chassis Intrusion Switch Tool-Free ODD/FDD/HDD Bay Clips Tool-Free Side Panel Clips

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*The actual product is subject to change without prior notice. In Win Development Inc. reserves the right to make final modifications.

Specification